

ABSTRACT

A window ball grid array (WBGA) semiconductor package and a fabrication method thereof are provided. This WBGA package includes: a substrate having a through opening; a chip mounted on an upper surface and over the opening of the substrate via an adhesive, and electrically connected to a lower surface of the substrate via bonding wires through the opening, with gaps, not applied with the adhesive, formed between the chip and the substrate; a first encapsulation body made of a resin material for encapsulating the chip and the bonding wires, allowing the resin material to pass through the gaps to fill the opening of the substrate and the gaps; a second encapsulation body for covering the part of the first encapsulation body on the lower surface of the substrate; and a plurality of solder balls bonded to area free of the second encapsulation body on the lower surface of the substrate.

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